

Digital FET, P-Channel

-25 V, -0.12 A, 10 Ω

FDV302P

General Description

This P-Channel logic level enhancement mode field effect transistor is produced using our proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance. This device has been designed especially for low voltage applications as a replacement for digital transistors. Since bias resistors are not required, this one P-channel FET can replace several digital transistors with different bias resistors such as the DTCx and DCDx series.

Features

- 25 V, -0.12 A Continuous, -0.5 A Peak
 - $R_{DS(on)} = 13 \Omega @ V_{GS} = -2.7 V$
 - $R_{DS(on)} = 10 \Omega @ V_{GS} = -4.5 V$
- Very Low Level Gate Drive Requirements Allowing Direct Operation in 3 V Circuits. $V_{GS(th)} < 1.5 V$
- Gate-Source Zener for ESD Ruggedness. > 6 kV Human Body Model
- Compact Industry Standard SOT-23 Surface Mount Package
- Replace Many PNP Digital Transistors (DTCx and DCDx) with One DMOS FET
- This Device is Pb-Free and Halide Free

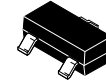
ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ C$ unless otherwise noted.

Symbol	Parameter	Value	Unit
V_{DSS}	Drain-Source Voltage	-25	V
V_{GSS}	Gate-Source Voltage	-8	V
I_D	Drain Current - Continuous	-0.12	A
	Drain Current - Pulsed	-0.5	
P_D	Maximum Power Dissipation	0.35	W
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to 150	$^\circ C$
ESD	Electrostatic Discharge Rating MIL-STD-883D Human Body Model (100 pF/1500 Ω)	6.0	kV

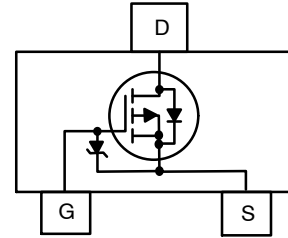
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS $T_A = 25^\circ C$ unless otherwise noted.

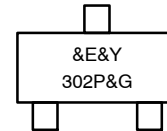
Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	357	$^\circ C/W$



SOT-23-3
CASE 318-08



MARKING DIAGRAM



&E = Designates Space
&Y = Binary Calendar Year Coding Scheme
302P = Specific Device Code
&G = Date Code

ORDERING INFORMATION

Device	Package	Shipping [†]
FDV302P	SOT-23-3 (Pb-Free, Halide-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](#).

FDV302P

ELECTRICAL CHARACTERISTICS $T_A = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

BV_{DSS}	Drain–Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = -250\ \mu\text{A}$	-25	-	-	V
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	$I_D = -250\ \mu\text{A}$, Referenced to 25°C	-	-20	-	mV/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -20\text{ V}, V_{GS} = 0\text{ V}$	-	-	-1	μA
		$V_{DS} = -20\text{ V}, V_{GS} = 0\text{ V}, T_J = 55^\circ\text{C}$	-	-	-10	
I_{GSS}	Gate – Body Leakage Current	$V_{GS} = -8\text{ V}, V_{DS} = 0\text{ V}$	-	-	-100	nA

ON CHARACTERISTICS (Note 1)

$\Delta V_{GS(th)}/\Delta T_J$	Gate Threshold Voltage Temp. Coefficient	$I_D = -250\ \mu\text{A}$, Referenced to 25°C	-	1.9	-	mV/ $^\circ\text{C}$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\ \mu\text{A}$	-0.65	-1	-1.5	V
$R_{DS(on)}$	Static Drain–Source On–Resistance	$V_{GS} = -2.7\text{ V}, I_D = -0.05\text{ A}$	-	10.6	13	Ω
		$V_{GS} = -4.5\text{ V}, I_D = -0.2\text{ A}$	-	7.9	10	
		$V_{GS} = -4.5\text{ V}, I_D = -0.2\text{ A}, T_J = 125^\circ\text{C}$	-	12	18	
$I_{D(on)}$	On–State Drain Current	$V_{GS} = -2.7\text{ V}, V_{DS} = -5\text{ V}$	-0.05	-	-	A
g_{FS}	Forward Transconductance	$V_{DS} = -5\text{ V}, I_D = -0.2\text{ A}$	-	0.135	-	S

DYNAMIC CHARACTERISTICS

C_{iss}	Input Capacitance	$V_{DS} = -10\text{ V}, V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}$	-	11	-	μF
C_{oss}	Output Capacitance		-	7	-	
C_{riss}	Reverse Transfer Capacitance		-	1.4	-	

SWITCHING CHARACTERISTICS (Note 1)

$t_{D(on)}$	Turn–On Delay Time	$V_{DD} = -6\text{ V}, I_D = -0.2\text{ A}, V_{GS} = -4.5\text{ V}, R_{GEN} = 50\ \Omega$	-	5	12	ns
t_r	Turn–On Rise Time		-	8	16	
$t_{D(off)}$	Turn–Off Delay Time		-	9	18	
t_f	Turn–Off Fall Time		-	5	10	
Q_g	Total Gate Charge	$V_{DS} = -5\text{ V}, I_D = -0.2\text{ A}, V_{GS} = -4.5\text{ V}$	-	0.22	0.31	nC
Q_{gs}	Gate–Source Charge		-	0.11	-	
Q_{gd}	Gate–Drain Charge		-	0.04	-	

DRAIN–SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS

I_S	Maximum Continuous Drain–Source Diode Forward Current	-	-	-0.2	A	
V_{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = -0.2\text{ A}$ (Note 1)	-	-1	-1.5	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width $\leq 300\ \mu\text{s}$, Duty Cycle $\leq 2.0\%$.

TYPICAL CHARACTERISTICS

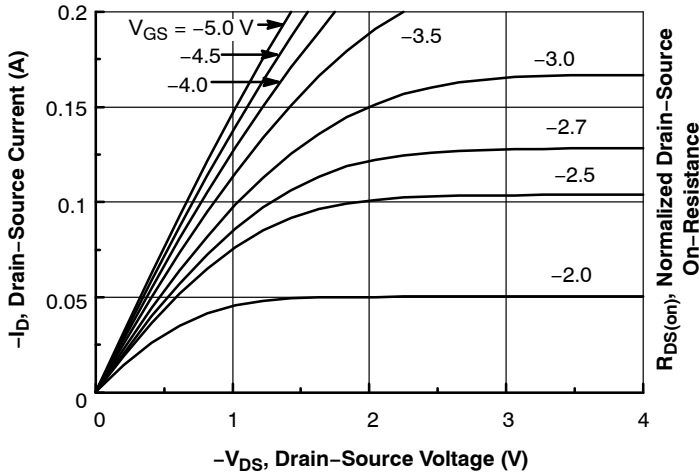


Figure 1. On-Region Characteristics

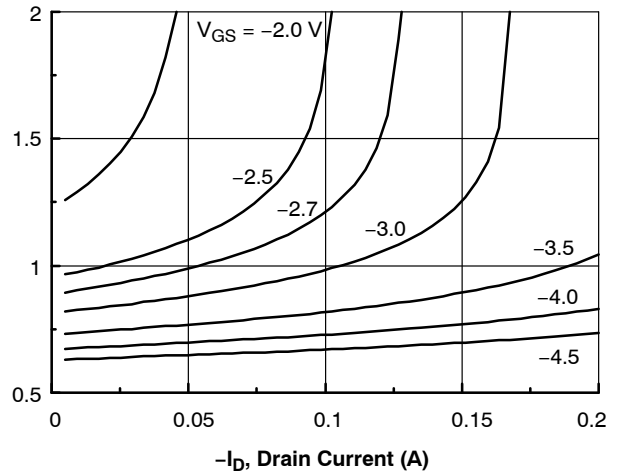


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

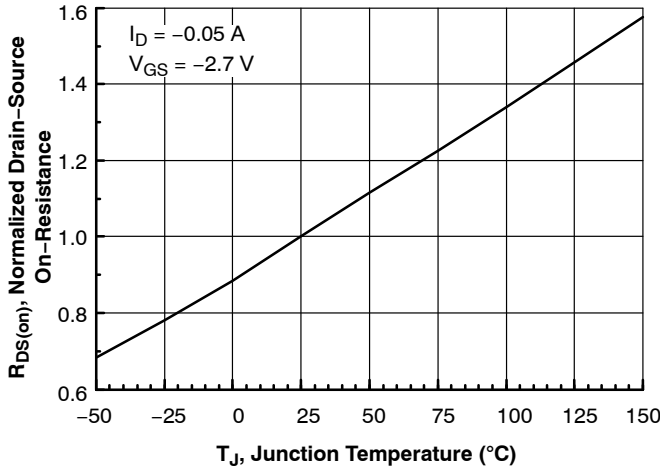


Figure 3. On-Resistance Variation with Temperature

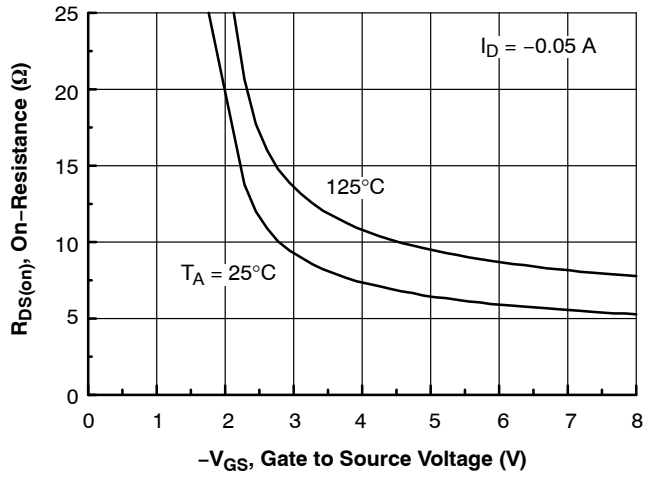


Figure 4. On Resistance Variation with Gate-To-Source Voltage

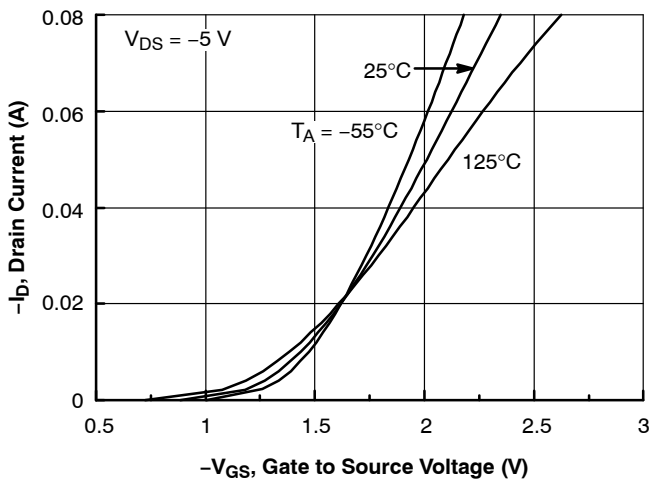


Figure 5. Transfer Characteristics

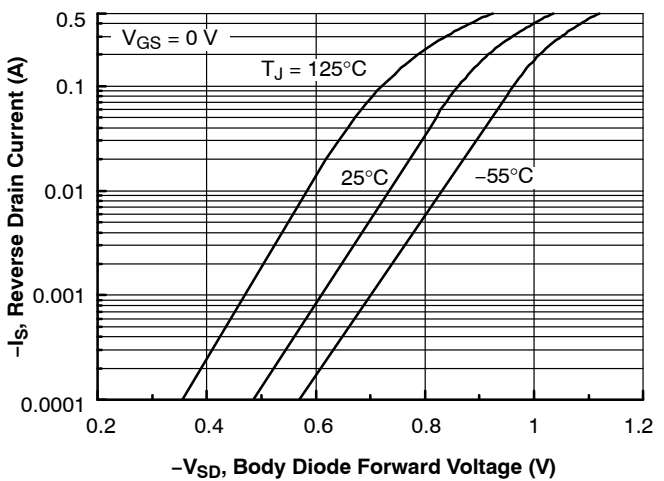


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

TYPICAL CHARACTERISTICS (continued)

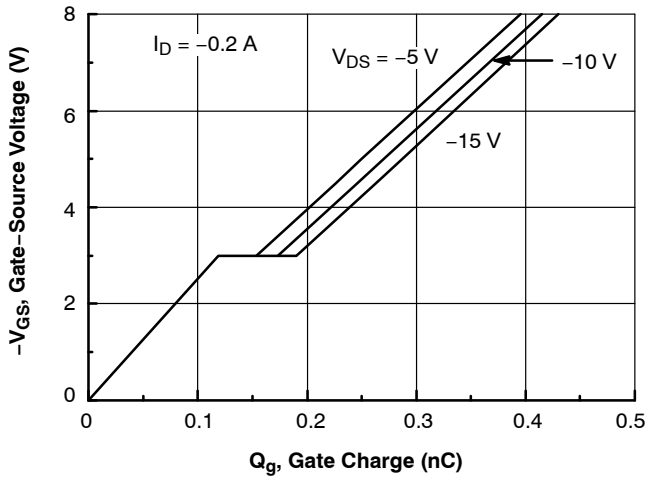


Figure 7. Gate Charge Characteristics

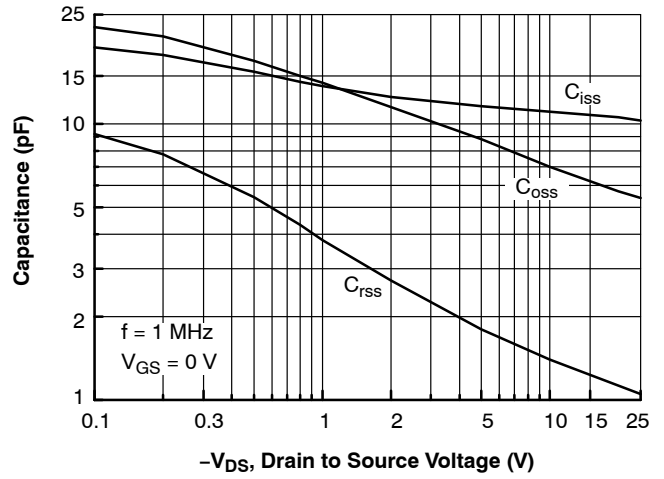


Figure 8. Capacitance Characteristics

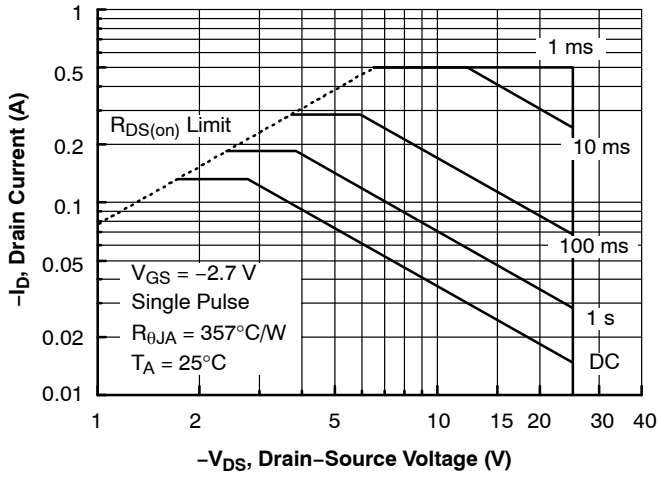


Figure 9. Maximum Safe Operating Area

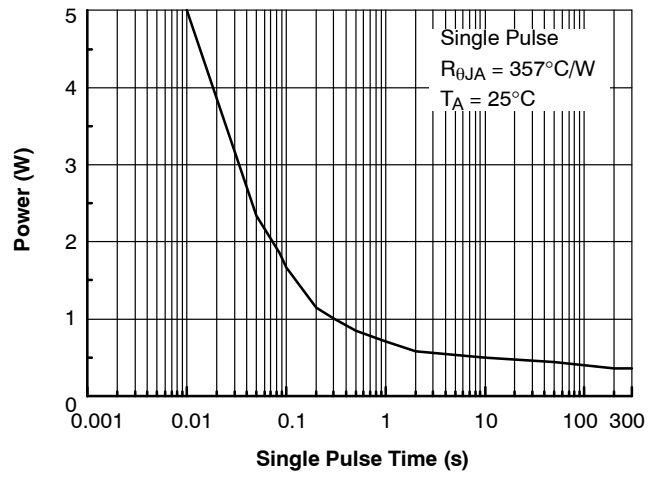


Figure 10. Single Pulse Maximum Power Dissipation

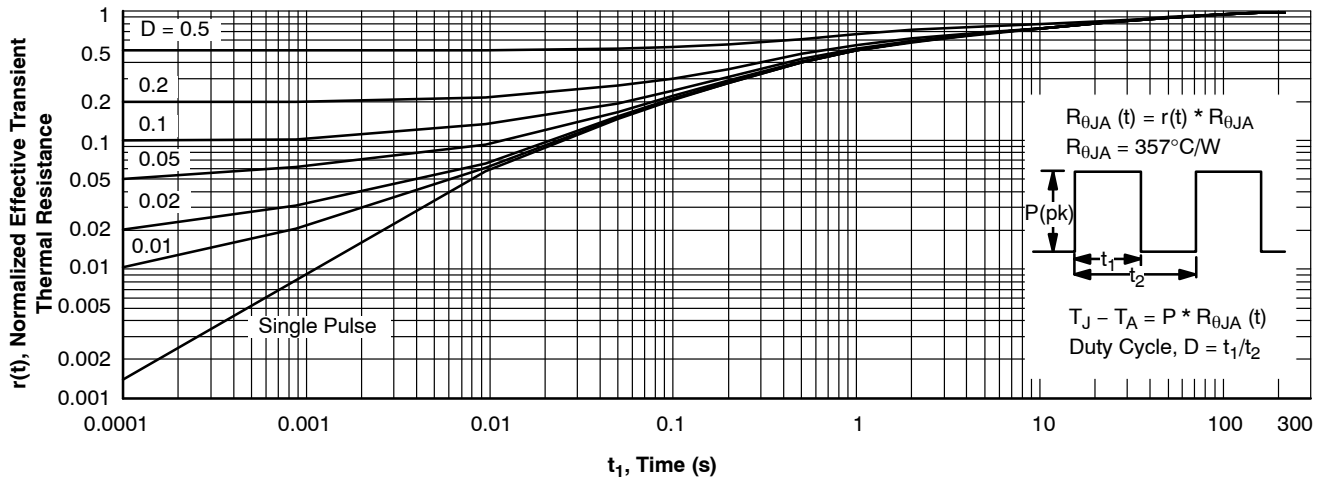


Figure 11. Transient Thermal Response Curve

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®



SOT-23 (TO-236) CASE 318-08 ISSUE AS

DATE 30 JAN 2018

SCALE 4:1



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
c	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
T	0°	---	10°	0°	---	10°

RECOMMENDED SOLDERING FOOTPRINT



GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

STYLE 1 THRU 5:
CANCELLED

STYLE 6:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

STYLE 7:
PIN 1. EMITTER
2. BASE
3. COLLECTOR

STYLE 8:
PIN 1. ANODE
2. NO CONNECTION
3. CATHODE

STYLE 9:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 10:
PIN 1. DRAIN
2. SOURCE
3. GATE

STYLE 11:
PIN 1. ANODE
2. CATHODE
3. CATHODE-ANODE

STYLE 12:
PIN 1. CATHODE
2. CATHODE
3. ANODE

STYLE 13:
PIN 1. SOURCE
2. DRAIN
3. GATE

STYLE 14:
PIN 1. CATHODE
2. GATE
3. ANODE

STYLE 15:
PIN 1. GATE
2. CATHODE
3. ANODE

STYLE 16:
PIN 1. ANODE
2. CATHODE
3. CATHODE

STYLE 17:
PIN 1. NO CONNECTION
2. ANODE
3. CATHODE

STYLE 18:
PIN 1. NO CONNECTION
2. CATHODE
3. ANODE

STYLE 19:
PIN 1. CATHODE
2. ANODE
3. CATHODE-ANODE

STYLE 20:
PIN 1. CATHODE
2. ANODE
3. GATE

STYLE 21:
PIN 1. GATE
2. SOURCE
3. DRAIN

STYLE 22:
PIN 1. RETURN
2. OUTPUT
3. INPUT

STYLE 23:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 24:
PIN 1. GATE
2. DRAIN
3. SOURCE

STYLE 25:
PIN 1. ANODE
2. CATHODE
3. GATE

STYLE 26:
PIN 1. CATHODE
2. ANODE
3. NO CONNECTION

STYLE 27:
PIN 1. CATHODE
2. CATHODE
3. CATHODE

STYLE 28:
PIN 1. ANODE
2. ANODE
3. ANODE

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